Electronic Supplementary Material (ESI) for Physical Chemistry Chemical Physics.
This journal is © the Owner Societies 2023

Supporting Information

Effect of flake silver-plated copper particles on properties enhancement of electronic conductive adhesives

Na Cheng[a], Zhi Sun[a], Xiaohui Yu[b*], Qianzhen Yu[a], Jianwei Zhao[a*]

[a] *College of Material and Textile Engineering, Key Laboratory of Yarn Materials Forming and Composite Processing Technology, Jiaxing University, Jiaxing 314001, Zhejiang, China*

[b] *College of Design, Jiaxing University, Jiaxing 314001, Zhejiang, China*

a) **b)**

Figure S1. The macroscopic morphology of (a) the pure silver particles and (b) the pure copper particles.

Figure S2. The surface morphology of (a) the pure silver particles and (b) the pure copper particles.